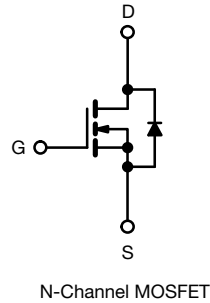
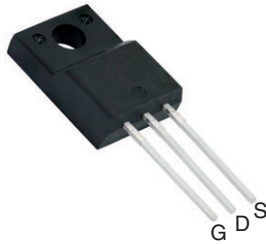


## E Series Power MOSFET with Fast Body Diode

**Thin-Lead TO-220 FULLPAK**


### FEATURES

- Fast body diode MOSFET using E series technology
- Reduced  $t_{rr}$ ,  $Q_{rr}$ , and  $I_{RRM}$
- Low figure-of-merit (FOM)  $R_{on} \times Q_g$
- Low input capacitance ( $C_{iss}$ )
- Low switching losses due to reduced  $Q_{rr}$
- Ultra low gate charge ( $Q_g$ )
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
Available

### APPLICATIONS

- Telecommunications
  - Server and telecom power supplies
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Consumer and computing
  - ATX power supplies
- Industrial
  - Welding
  - Battery chargers
- Renewable energy
  - Solar (PV inverters)
- Switch mode power supplies (SMPS)
- Applications using the following topologies
  - LCC
  - Phase shifted bridge (ZVS)
  - 3-level inverter
  - AC/DC bridge

PRODUCT SUMMARY	
$V_{DS}$ (V) at $T_J$ max.	700
$R_{DS(on)}$ max. ( $\Omega$ ) at 25 °C	$V_{GS} = 10$ V   0.156
$Q_g$ max. (nC)	122
$Q_{gs}$ (nC)	17
$Q_{gd}$ (nC)	36
Configuration	Single

### ORDERING INFORMATION

Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free	SiHA24N65EF-E3
Lead (Pb)-free and halogen-free	SiHA24N65EF-GE3

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)


PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	$V_{DS}$	650	V
Gate-source voltage	$V_{GS}$	$\pm 30$	
Continuous drain current ( $T_J = 150$ °C) <sup>e</sup>	$V_{GS}$ at 10 V	$T_C = 25$ °C	A
		$T_C = 100$ °C	
Pulsed drain current <sup>a</sup>	$I_{DM}$	65	
Linear derating factor		0.31	W/°C
Single pulse avalanche energy <sup>b</sup>	$E_{AS}$	691	mJ
Maximum power dissipation	$P_D$	39	W
Operating junction and storage temperature range	$T_J, T_{stg}$	-55 to +150	°C
Drain-source voltage slope	$dV/dt$	$T_J = 125$ °C	70
Reverse diode $dV/dt$ <sup>d</sup>		50	
Soldering recommendations (peak temperature) <sup>c</sup>	for 10 s	300	°C
Mounting torque	M3 screw	0.6	Nm

#### Notes

- Repetitive rating; pulse width limited by maximum junction temperature
- $V_{DD} = 50$  V, starting  $T_J = 25$  °C,  $L = 28.2$  mH,  $R_g = 25$   $\Omega$ ,  $I_{AS} = 7$  A
- 1.6 mm from case
- $I_{SD} \leq I_D$ ,  $dI/dt = 900$  A/ $\mu$ s, starting  $T_J = 25$  °C
- Limited by maximum junction temperature



THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R <sub>thJA</sub>	-	65	°C/W
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	3.2	

SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
<b>Static</b>							
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA		650	-	-	V
V <sub>DS</sub> temperature coefficient	ΔV <sub>DS</sub> /T <sub>J</sub>	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.68	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		2	-	4	V
Gate-source leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
		V <sub>GS</sub> = ± 30 V		-	-	± 1	μA
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 520 V, V <sub>GS</sub> = 0 V		-	-	1	μA
		V <sub>DS</sub> = 520 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		-	-	500	
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 12 A	-	0.13	0.156	Ω
Forward transconductance	g <sub>fs</sub>	V <sub>DS</sub> = 30 V, I <sub>D</sub> = 12 A		-	7.2	-	S
<b>Dynamic</b>							
Input capacitance	C <sub>iSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 100 V, f = 1 MHz		-	2774	-	pF
Output capacitance	C <sub>oss</sub>			-	128	-	
Reverse transfer capacitance	C <sub>rSS</sub>			-	4	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>			-	96	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>	V <sub>DS</sub> = 0 V to 520 V, V <sub>GS</sub> = 0 V		-	333	-	
Total gate charge	Q <sub>g</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 12 A, V <sub>DS</sub> = 520 V	-	81	122	nC
Gate-source charge	Q <sub>gs</sub>			-	17	-	
Gate-drain charge	Q <sub>gd</sub>			-	36	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 520 V, I <sub>D</sub> = 12 A, V <sub>GS</sub> = 10 V, R <sub>g</sub> = 9.1 Ω		-	24	48	ns
Rise time	t <sub>r</sub>			-	34	68	
Turn-off delay time	t <sub>d(off)</sub>			-	80	120	
Fall time	t <sub>f</sub>			-	46	92	
Gate input resistance	R <sub>g</sub>	f = 1 MHz, open drain		0.2	0.5	1.0	Ω
<b>Drain-Source Body Diode Characteristics</b>							
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	24	A
Pulsed diode forward current	I <sub>SM</sub>			-	-	65	
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 12 A, V <sub>GS</sub> = 0 V		-	0.9	1.2	V
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 12 A, di/dt = 100 A/μs, V <sub>R</sub> = 400 V		-	151	288	ns
Reverse recovery charge	Q <sub>rr</sub>			-	0.9	2.1	μC
Reverse recovery current	I <sub>RRM</sub>			-	13	-	A

**Notes**

- a. C<sub>oss(er)</sub> is a fixed capacitance that gives the same energy as C<sub>oss</sub> while V<sub>DS</sub> is rising from 0 % to 80 % V<sub>DSS</sub>
- b. C<sub>oss(tr)</sub> is a fixed capacitance that gives the same charging time as C<sub>oss</sub> while V<sub>DS</sub> is rising from 0 % to 80 % V<sub>DSS</sub>

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

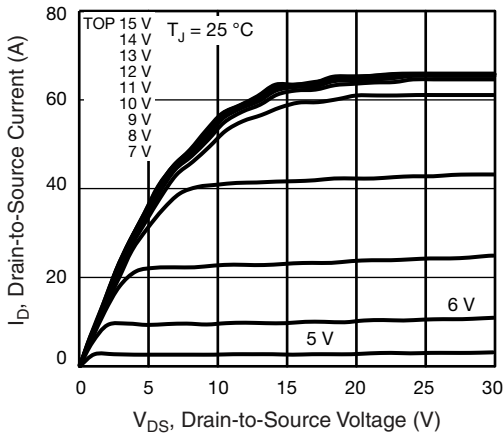


Fig. 1 - Typical Output Characteristics

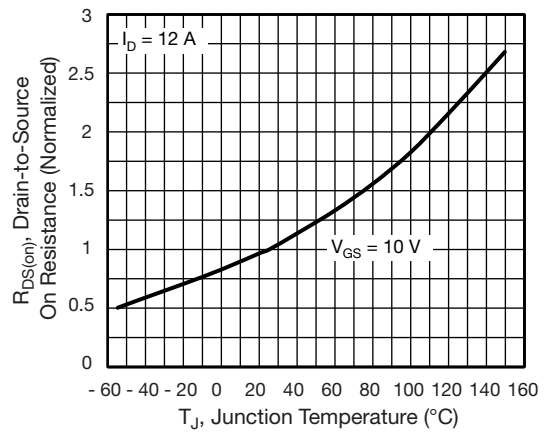


Fig. 4 - Normalized On-Resistance vs. Temperature

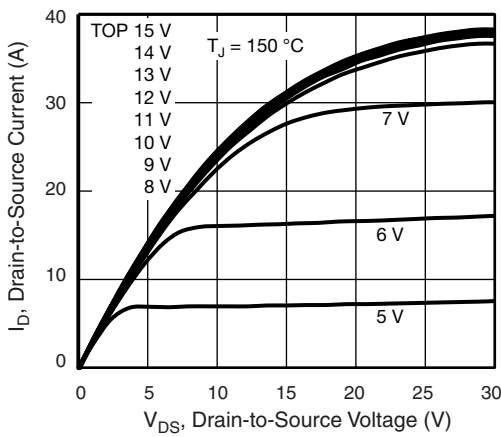


Fig. 2 - Typical Output Characteristics

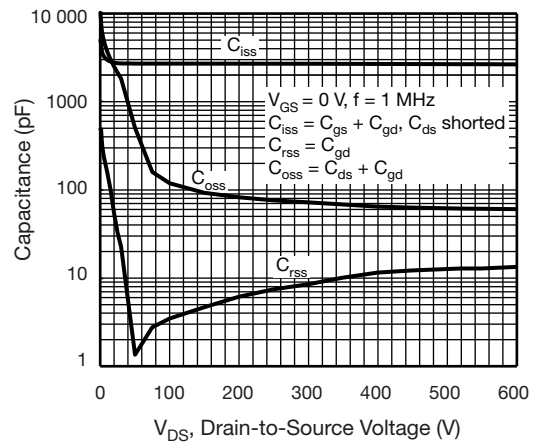


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

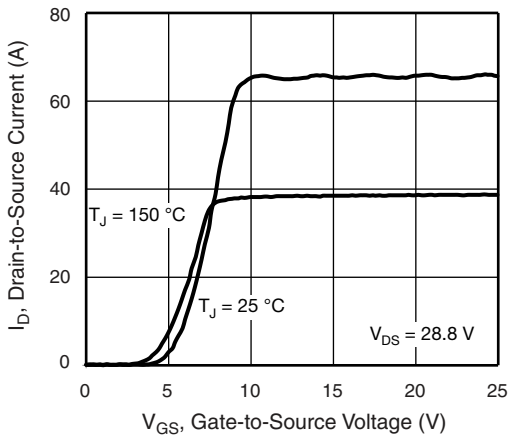


Fig. 3 - Typical Transfer Characteristics

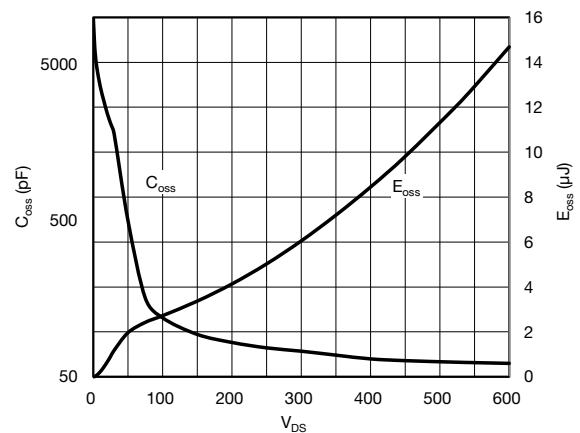


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$

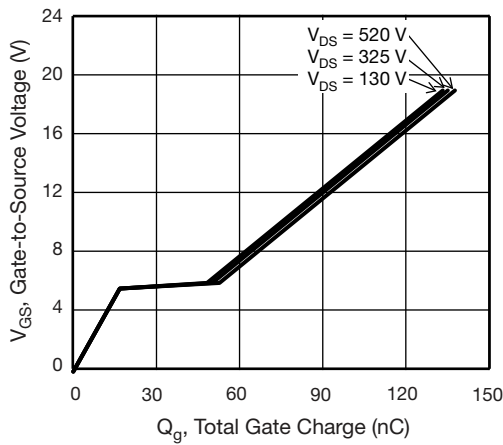


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

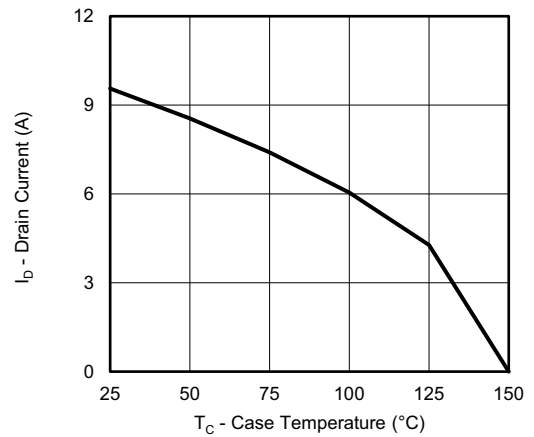


Fig. 10 - Maximum Drain Current vs. Case Temperature

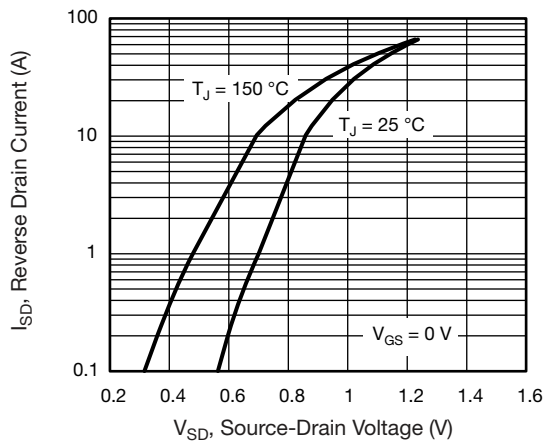


Fig. 8 - Typical Source-Drain Diode Forward Voltage

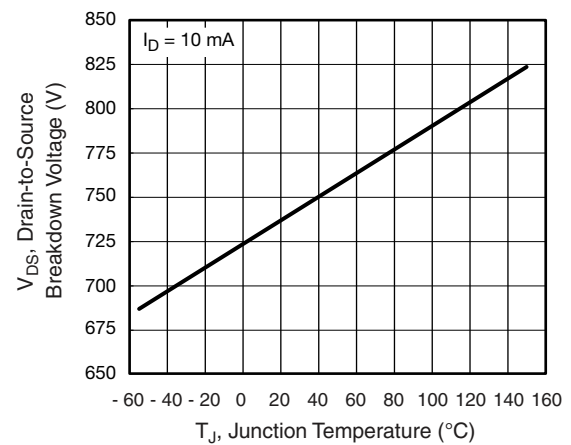


Fig. 11 - Temperature vs. Drain-to-Source Voltage

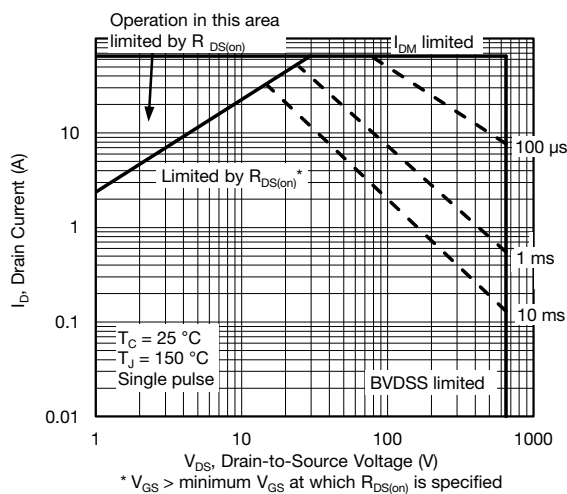


Fig. 9 - Maximum Safe Operating Area

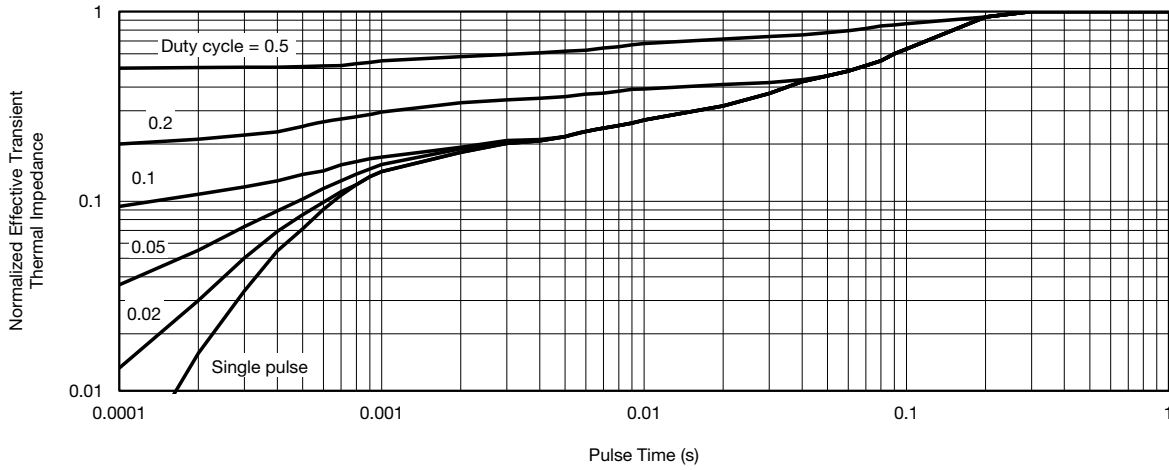


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

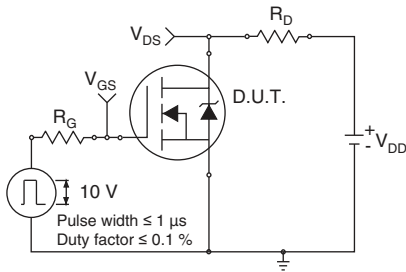


Fig. 13 - Switching Time Test Circuit

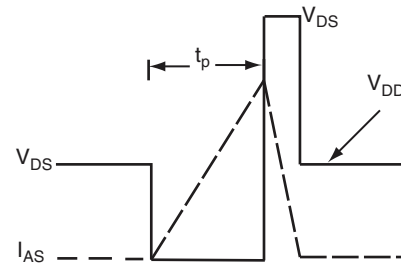


Fig. 16 - Unclamped Inductive Waveforms

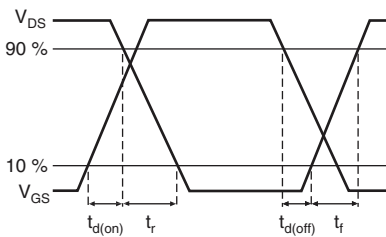


Fig. 14 - Switching Time Waveforms

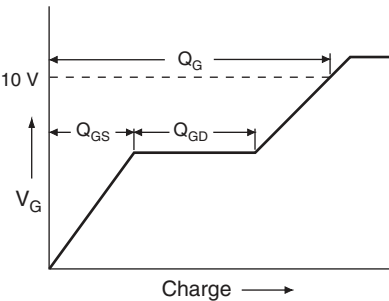


Fig. 17 - Basic Gate Charge Waveform

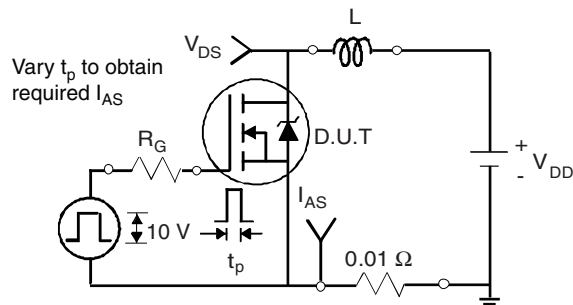


Fig. 15 - Unclamped Inductive Test Circuit

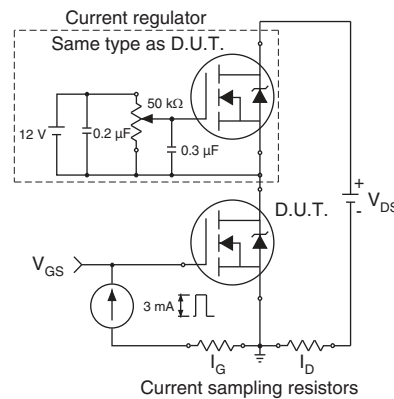
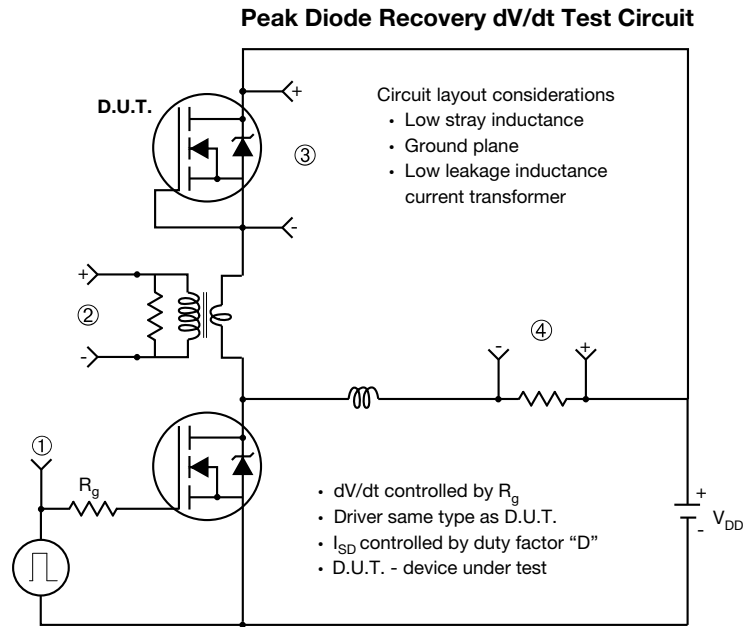


Fig. 18 - Gate Charge Test Circuit



**Note**

a.  $V_{GS} = 5 V$  for logic level devices

Fig. 19 - For N-Channel

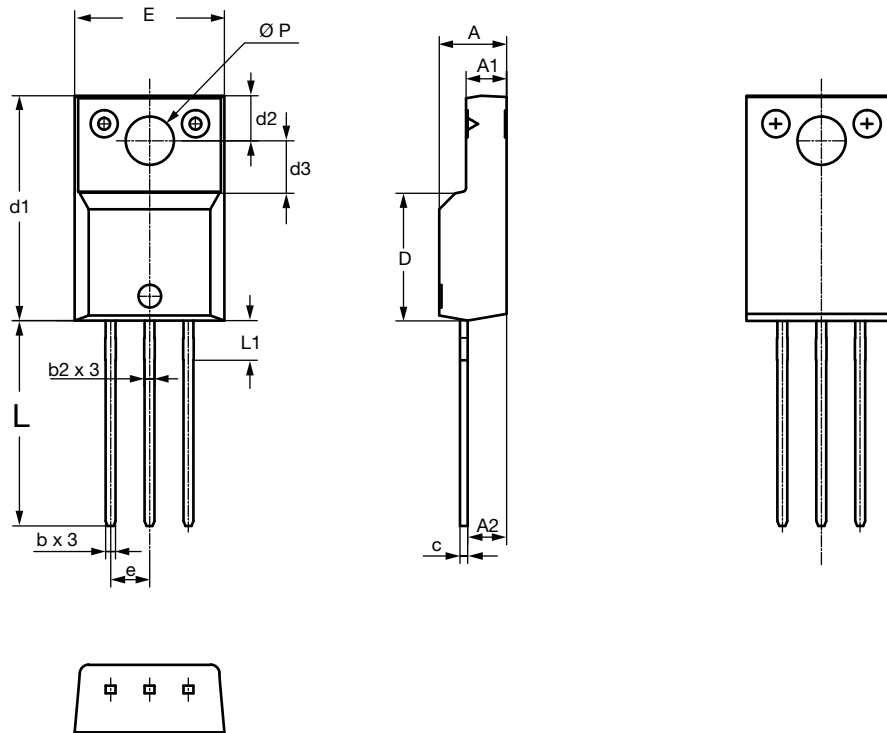
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### TO-220 FULLPAK Thin Lead



SYMBOL	DIMENSIONS			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.30	4.70	0.169	0.185
A1	2.50	2.90	0.098	0.114
A2	2.40	2.80	0.094	0.110
b	0.60	0.80	0.024	0.031
b2	0.60	0.90	0.024	0.035
c	-	0.60	-	0.024
D	8.30	8.70	0.327	0.342
d1	14.70	15.30	0.579	0.602
d2	2.90	3.10	0.114	0.122
d3	3.30	3.70	0.130	0.146
E	9.70	10.30	0.382	0.406
e	2.50	2.70	0.098	0.106
L	13.40	13.80	0.528	0.543
L1	1.00	2.80	0.039	0.110
$\varnothing P$	3.00	3.40	0.118	0.134

ECN: E20-0684-Rev. D, 28-Dec-2020  
DWG: 6021





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